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Author Correction: Elastic pseudospin transport for integratable topological phononic circuits

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The original version of this Article contained errors in the second sentence in the legend of Fig. 1, which incorrectly read 'These two elastic insulators are identical in lattice constant *a* (3*a*₀), plate thickness (0.4*a*₀), and radius of perforated holes *r* (0.18*a*₀) but different hole-center distance characterized by *b*.' The correct version states 'plate thickness ($\sqrt{3} \times 0.4a_0$)' in place of 'plate thickness (0.4*a*₀), and 'radius of perforated holes *r* ($\sqrt{3} \times 0.18a_0$)' rather than 'radius of perforated holes *r* (0.18*a*₀)'.

The first sentence of the 'Sample preparation' section of the Methods originally incorrectly read 'Our samples are prepared exclusively on polished stainless-steel plates (Type 201, mass density 7803 kg m⁻³) with a fixed plate thickness 7.82 mm.' In the corrected version, 'mass density 7903 kg m⁻³' replaces 'mass density 7803 kg m⁻³'.

The second sentence in the legend of Supplementary Fig. 3, originally incorrectly read 'The symmetry of the phononic crystal remains unchanged as $C_{6\nu}$, and thickness of the substrates *H* (equals to $0.4a_0$), lattice constant a (equals to $3a_0$) and radius of perforated holes *r* (equals to $0.18 a_0$) maintain constant.' The correct version states ' $\sqrt{3} \times 0.4a_0$ ' in place of ' $0.4a_0$ ' and ' $\sqrt{3} \times 0.18a_0$ ' rather than ' $0.18a_0$ '.

This has been corrected in both the PDF and HTML versions of the Article.

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